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# Application form - Pact for Skills

Fields marked with \* are mandatory.

#### Introduction

The Pact for Skills is a shared engagement and approach to skills development. It is firmly anchored in the principles of the <u>European Pillar of Social Rights</u> and supports the goals of the <u>Green Deal</u> and the <u>digital</u> transformation, as set out in the Commission communication "A strong Social Europe for Just Transitions".

The Pact aims to mobilise and incentivise private and public stakeholders to take concrete action for the **up skilling and reskilling of people of working age**, and, when relevant, pool efforts in the partnerships.

The Pact can be joint by any private or public organisation or partnership of organisations which aim to upskill or reskill people of working age.

The organisation(s) need(s) to be based in one of the Member States, EFTA or candidate countries.

#### Joining the Pact:

- 1. All stakeholders joining the Pact **sign up to the Charter** and its key principles, which they agree to respect and uphold.
- 2. Signatories of the Pact are invited to **translate their engagement into concrete commitments** on upskilling and reskilling. Commitments must be in line with the key principles and can be built around a number of "enablers" that illustrate concrete ways of implementing the different principles.
- 3. Commitments are monitored by at least one **key performance indicator**, e.g. number of people taking part in upskilling or reskilling.

### Information on the organisation/partnership

### \* You apply:

- on your own (as one organisation)
- in partnership

APTE - Association for Promoting	Electronics Technology
nat type of stakeholder does	s your organisation represent?
Large employer (more than 250 employees)	
Micro, small or medium employe (up to 249 employees)	
<ul><li>Public authority (local, regional onational)</li></ul>	
Private or public employment services	Training provider
Trade union (social partner)	<ul> <li>Representative of an industrial cluster (member of a groups of specialised enterprises, often SMEs, and other related supporting actors in a location that cooperate closely)</li> </ul>
ountry/ies in which the organ	nisation/partnership operates:
Romania	
Paul Svasta, President; Bogdan M Member;	lihailescu, Executive Director; Zsolt Illyefalvi-Vitéz, Corresponding
noil to contact paraons	
zsolt.illyefalvi@apte.org.ro	
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Construction		Health	Retail
Creative and Cultural Industries	<b>V</b>	Mobility-Transport-Automotive	Textiles
Digital		N/A	Tourism

#### \*Give a short description of your organisation/partnership

1000 character(s) maximum

APTE, the Association for Promoting Electronics Technology (apte.org.ro) has 88 members, represents IMAPS Romania and manages the Electronics Innovation Cluster (elinclus.ro). APTE was founded in 2002 by UPB-CETTI, Center for Technological Electronics and Interconnection Techniques of University Politehnica of Bucharest (cetti.ro) together with highly respected members of the electronics industry. The mission of APTE is to train a globally-competitive workforce with theoretical and hands-on education in the areas of science, engineering, microelectronics and packaging, covering also business, economics, ethics, foreign culture and languages.

APTE organizes annually international technical and scientific events such as TIE, a student contest of Design of Electronic Modules and Assemblies (tie.ro) and SIITME, the IEEE International Symposium for Design and Technology in Electronic Packaging (siitme.ro).

APTE was awarded twice by the 'silver label' Cluster Management Excellence of ESCA.

### Signing up to the Charter

Please confirm your organisation/partnership subscribes to the <u>Charter of the Pact for Skills</u>, understand and share the principles of quality upskilling and reskilling. Signature of the Charter does not constitute an endorsement of the signatory organisation and its activities by the European Commission.

#### Commitment

#### \* Would you like to join the Pact with concrete commitment?

Commitment is a concrete action (set of actions), which aims to upskill or reskill people of working age. In the file you can find a <u>non-exhaustive list of actions</u> that could be implemented under the Pact for Skills.

Yes

O No

Non-exhaustive list of actions that could be implemented under the Pact for Skills.

Non-exhaustive\_list\_of\_actions.pdf

### Please provide information on your commitment

If you have more than 5 actions under your commitment please contact us at EC-PACT-FOR-SKILLS@ec.europa.eu.

	Action in the commitment	Organisation/person/team responsible for implementation of the action	Target group of the action	How the implementation of the action will be monitored
1	TIE - Interconnection Techniques in Electronics	Prof. Norocel CODREANU, Politehnica University of Bucharest	The TIE contest is organized for BSc, MSc and PhD students by 12-15 Universities interested to participate in TIE. (For 10-40 students per university, a total ca. 300 students). The contest has two stages: (1) local stage, which takes place in each university; 2. final stage, which takes place in a university of different cities each year, selected by the steering committee. The final stage is a two-and- half day event with the local winner students of total ca. 40. The performances of the contestants are evaluated by the Industrial and the Technical Committees.	TIE is monitored and the winners of the contest are rewarded by the Industrial Committee; Chairman: Cristian GORDAN, Continental Automotive, Timişoara

	TIE PLUS - The Step Towards Interconnect Simulation Technology	Cătălin NEGREA, PhD, Continental Automotive, Timişoara	mainly MSc and PhD students, maybe young industrial engineers. Their registration should be promoted by a University. The total number of the registered contestants is about twenty per year. They should solve a live industrial problem.  A set of data required to solve the subject is published on an online platform. This marks the beginning of the "subject solving period" of about two weeks. Each contestant should go through the necessary simulation, design and documentation steps with the goal of delivering a technical solution to the problem. The result should be summarized in a technical report and uploaded for evaluation. If the Industrial and the Technical Committees consider the content is adequate for the final evaluation process, the contestant is required to prepare a short presentation (20-25 min.) that will be exposed to the Committees and a larger audience during an evaluation meeting. If the Industrial and the Technical Committees consider the content is adequate for the final evaluation process, the contestant is required to prepare a short presentation (20-25 min.) that will be exposed to prepare a short presentation (20-25 min.) that will be	TIE Plus is monitored and the winners of the contest are rewarded by the Industrial Committee, Chairman: Cosmin Moisă, Continental Automotive, Timişoara, Romania
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3	SIITME - IEEE International Symposium for Design and Technology in Electronic Packaging	Prof. Paul Svasta General Chair, Politehnica University of Bucharest	The IEEE SIITME conference is a powerful and reliable forum, where specialists in the electronics industry come into direct contact with researchers and academics, for the benefit of both parties and with a significant impact on technological development. The particularly important role of this scientific event is to encourage and support the integration of young researchers in the main stream of scientific manifestations. During the conference, many opportunities are created for them to come in contact with distinguished researchers, to expose their ideas in front of an informed audience and to practice and improve their communication and reasoning skills. The number of participants is about 150 per year, of which approx. 60 are young students, researchers or engineers, and the rest are academics and industrial experts. Best and excellent presentations are rewarded with a special focus on rewarding the young presenters.  Life-long learning of the participants of all ages is promoted by professional development course and keynote presentations of world-wide recognized experts.	The organization is managed and monitored by the steering Committee. The submitted publications are reviewed and selected by the Publication Committee with the help of the Scientific Committee and international experts, using the Microsoft Conference Management Toolkit. Papers meeting quality criteria are indexed IEEE Xplore Digital Library and Thomson-Reuters ISI-CPCI.
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5	BRIDGE - Building Relations to go International for Data-Driven Growing Enterprises (start-ups and SMEs) (https://www.clustercollaboration.eu/escp- profiles/bridge). Participation in the BRIDGE Project with the objectives to establish a European Strategic Clusters Partnership (ESCP) to promote clusters internationalization by developing a joint international strategy aimed at supporting deep tech start-ups and SMEs from the Data-Driven industry, using Artificial intelligence, blockchain and future emerging data-driven technologies, and to intensify clusters and network collaboration across borders. There are two main goals of the action: (1) to share knowledge and expertise; and (2) to build a portfolio of competitive services to support start-ups and SMEs.	The BRIDGE project partners are: Fondazione Torino Wireless (TOWL-IT), Baden-Württemberg: Connected (bwcon- DE), Association for Promoting Electronics Technology representing Electronics Innovation Cluster (APTE – ELINCLUS - RO) and Foundation Cluster Information and Communication Technologies (ICT Cluster - BG). On behalf of APTE - Romania: Prof. Paul Svasta PhD, President; Eng Bogdan Mihăilescu PhD, Executive Manager and Cristina Lepădatu, Assistant Executive Manager are responsible for the implementation of the Project.	The BRIDGE Consortium represents a total of circa 1,100 SMEs, and the BRIDGE project expects by the end of the 20 months of its duration to account the participation of 200 EU Cluster organisations, start-ups and SMEs which will have benefited from the actions developed during the project: events, workshops, joint-strategies, partnership agreements, etc.	The implementation of the action will be monitored by reports, partnership agreements, events and workshops at the execution of the following steps of the Project: (1) Creating a BRIDGE Value Chain composed by European start-ups and SMEs working on data-driven technologies (Artificial Intelligence and Blockchain); (2) Developing a joint internationalization strategy shared by European Clusters interested in supporting their companies in approaching new markets in new countries; (3) Validate the strategy and its support measures with the involved companies through coparticipative laboratories and workgroups; (4) Creating a European Strategic Cluster Partnership to formalize and strengthen the commitment between the partners to take the BRIDGE Value Chain abroad.

* Starting	date:
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01/01/2021

# End date (if applicable):

31/12/2025

# Key performance indicators

Name of the indicator	Value (only numerical value)	Additional description (if needed)
Number of representatives of the target group who take part in up-/re-skilling (per year)	440	TIE: number of participants >300 students/year TIE Plus: number of participants >20 young researcher-engineers/year SIITME: number of participants >120, including more than 50 students BRIDGE: The BRIDGE Consortium represents a total of ca 1,100 SMEs, and the BRIDGE project expects by the end of the 20 months of its duration to account the participation of 200 EU Cluster organizations, start-ups and SMEs.
Others	TIE: The score limit for the finalist students, on the basis of which they receive a qualified certificate of achievement, and the bests receive awards. Actual score limits are set annually by the Technical Committee.  TIE Plus: Score limits are determined for the contestants, based on which they may receive qualified certificates of achievement. The bests can receive various awards, cash prizes, and occasionally job offers from the Awards Committee formed by industry professionals. The actual awards and the score limits are determined jointly by the Technical Committee and the Award Committee on an annual basis.  SIITME: As a general recognition of the achievements of the participants, papers meeting quality criteria are included into the indexed IEEE Xplore Digital Library and Thomson-Reuters ISI-CPCI. In addition, the best and excellent presentations/posters are rewarded, with a special attention on rewarding the young presenters.  BRIDGE: The number of the participating EU Cluster organizations, start-ups and SMEs.	

■ I agree to provide updates on activities related to this commitment, in the regular annual survey on Pact for Skills. If there is no participation in the survey, the commitment will be considered to be inactive.
☑ I confirm I have agreement of all partners to represent them in the Pact for Skills.
☑ I accept the privacy statement presented below.
Privacy statement
Privacy_statement.pdf
Thank you
Please do not change information below
Status of the application  Output  Output  Description  Output  Descript
Status of the application
Status of the application  Output  Out
Status of the application  Accepted  Under revision
Status of the application <ul> <li>Accepted</li> <li>Under revision</li> <li>Suspended</li> </ul>

### Contact

**Contact Form**